# S102S01/S102S02 S202S01/S202S02

# SIP Type SSR for Medium **Power Control**

#### **■** Features

- 1. High radiation resin mold package
- 2. RMS ON-state current

 $I_T$ : 8 Arms at  $T_C \le 80^{\circ}$ C (With heat sink)

- 3. Built-in zero-cross circuit (S102S02/S202S02)
- 4. High repetitive peak OFF-state voltage S102S01/S102S02 V<sub>DRM</sub>: MIN. 400V S202S01/S202S02 V DRM: MIN. 600V
- 5. Isolation voltage between input and output  $(V_{iso}: 4000V_{rms})$
- 6. Approved by CSA, No. LR63705 Recognized by UL, file No. E94758

■ Absolute Maximum Ratings

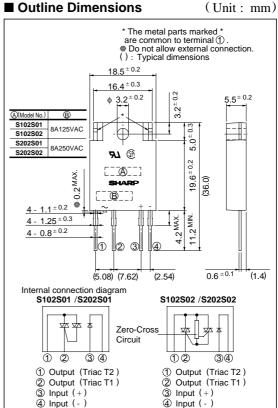
# ■ Applications

- 1. Automatic vending machines, programmable controllers
- 2. Amusement equipment

#### **■ Model Line-ups**

	For 100V lines	For 200V lines
For phase control No built-in zero-cross circuit	S102S01	S202S01
Built-in zero-cross circuit	S102S02	S202S02

#### **■** Outline Dimensions



# $(Ta = 25^{\circ}C)$

Parameter		Symbol	Rating  S102S01 S202S01 S102S02 S202S02		Unit
Input	Forward current	$I_F$	50		mA
	Reverse voltage	V <sub>R</sub>	6		V
Output	*1RMS ON-state current	rent I <sub>T</sub> 8		3	A rms
	*2Peak one cycle surge current	I surge	80		A
	Repetitive peak OFF-state voltage	$V_{DRM}$	400	600	V
	Non-repetitive peak OFF-state voltage	$V_{DSM}$	400	600	V
	Critical rate of rise of ON-state current	dI/dt	50		A/μ s
	Operating frequency	f	45 to 65		Hz
*3 Isolation voltage		$V_{iso}$	4 000		V <sub>rms</sub>
Operating temperature		T opr	- 25 to + 100		°C
Storage temperature		T stg	- 30 to + 125		°C
*4Soldering temperature		T sol	260		°C

 $*1 T_C <= 80^{\circ}C$ 

\*2 50Hz sine wave,  $T_j = 25^{\circ}C$ start

\*3 60Hz AC for 1 minute, 40 to 60% RH, Apply voltages between input and output, by the dielectric withstand voltage tester with zerocross circuit.

(Input and output shall be shorted respectively).

When the isolation voltage is necessary at using external heat sink, please use the insulation sheet. \*4 For 10 seconds

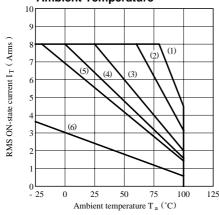
In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that occur in equipment using any of SHARP's devices, shown in catalogs data books, etc. Contact SHARP in order to obtain the latest version of the device specification sheets before using any SHARP's device

### **■** Electro-optical Characteristics

 $(Ta = 25^{\circ}C)$ 

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Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		V <sub>F</sub>	$I_F = 20mA$	-	1.2	1.4	V
	Reverse current		$I_R$	$V_R = 3V$	-	-	10-4	A
Output	Repetitive peak OFF-sta	ate current	I <sub>DRM</sub>	$V_D = V_{DRM}$	-	-	10-4	A
	ON-state voltage		V <sub>T</sub>	Resistance load I <sub>F</sub> = 20mA, I <sub>T</sub> = 2Arms	-	-	1.5	V <sub>rms</sub>
	Holding current		I <sub>H</sub>	-	-	-	50	mA
	Critical rate of rise of OFF-sta	te voltage	dV/dt	$V_D = 2/3 \cdot V_{DRM}$	30	-	-	V/μ s
	Critical rate of rise of co OFF-state voltage	ommutating	(dV/dt) <sub>C</sub>	$T_j = 125$ °C, dI <sub>T</sub> /dt= - 4.0A/ms, $V_D = 400V$	5	-	-	V/μ s
	Zero-cross voltage	S102S02 S202S02	V <sub>ox</sub>	$I_F = 8mA$	-	-	35	V
Transfer characteristics	Minimum	S102S01 S202S01	I <sub>FT</sub>	$V_D = 12V$ , $R_L = 30\Omega$	-	-	8	mA
	trigger current	S102S02 S202S02		$V_D = 6V, R_L = 30\Omega$	-	-	8	mA
	Isolation resistance		R <sub>ISO</sub>	DC500V, 40 to 60 % RH	1010	-	-	Ω
	Turn-on	S102S01 S202S01	t on	AC 50Hz	-	-	1	ms
	time	S102S02 S202S02			-	-	10	ms
	Turn-off time		t off	-	-	-	10	ms
Thermal resistance (Between junction and case)		R <sub>th(j-c)</sub>	-	-	4.5	-	°C/W	
Thermal resistance (Between junction and ambience)		R <sub>th(j-a)</sub>	-	-	40	-	°C/W	

Fig. 1 RMS ON-state Current vs. **Ambient Temperature** 



- (1) With infinite heat sink
- (1) With intinthe heat sink (200 x 200 x 2 mm Al plate) (3) With heat sink (100 x 100 x 2 mm Al plate) (4) With heat sink (75 x 75 x 2 mm Al plate) (5) With heat sink (50 x 50 x 2 mm Al plate)

- (5) With heat sink (50 x 50 x 2 mm Al plate)
  (6) Without heat sink
  (Note) With the Al heat sink set up vertically, tighten the device at the center of the Al heat sink with a torque of 0.4N m and apply thermal conductive silicone grease on the heat sink mounting plate. Forcible cooling shall not be carried out.

Fig. 2 RMS ON-state Current vs. Case Temperature

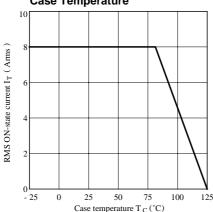


Fig. 4 Forward Current vs. Forward Voltage

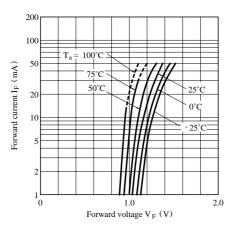
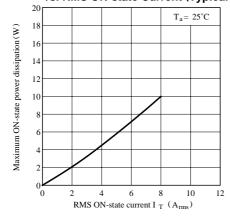


Fig. 6 Maximum ON-state Power Dissipation vs. RMS ON-state Current (Typical Value)



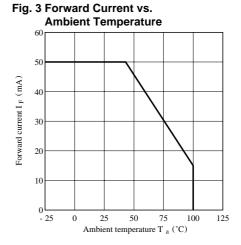


Fig. 5 Surge Current vs. Power-on Cycle

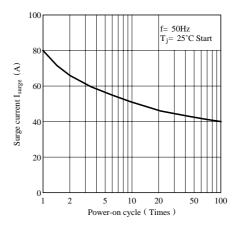


Fig. 7 Minimum Trigger Current vs.
Ambient Temperature (Typical Value)

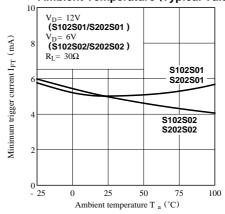
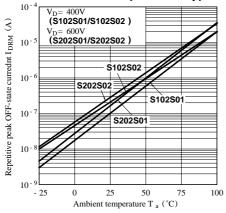


Fig. 8 Repetitive Peak OFF-state Current vs. Ambient Temperature (Typical Value)



• Please refer to the chapter "Precautions for Use"